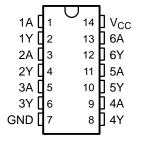


FEATURES

- Operates From 2.3 V to 3.6 V
- Max t_{pd} of 3.4 ns at 3.3 V
- ±24-mA Output Drive at 3.3 V
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

D, DGV, NS, OR PW PACKAGE (TOP VIEW)



DESCRIPTION/ORDERING INFORMATION

This hex Schmitt-trigger inverter is designed for 2.3-V to 3.6-V V_{CC} operation.

The SN74ALVC14 contains six independent inverters and performs the Boolean function $Y = \overline{A}$.

ORDERING INFORMATION

T _A	Р	ACKAGE ⁽¹⁾	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
	SOIC - D	Tube	SN74ALVC14D	ALVC14	
	30IC - D	Tape and reel	SN74ALVC14DR	ALVO14	
-40°C to 85°C	SOP - NS	Tape and reel	SN74ALVC14NSR	ALVC14	
	TSSOP - PW	Tape and reel	SN74ALVC14PWR	VA14	
	TVSOP - DGV	Tape and reel	SN74ALVC14DGVR	VA14	

⁽¹⁾ Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (each inverter)

INPUT A	OUTPUT Y
Н	L
L	Н

LOGIC DIAGRAM, EACH INVERTER (POSITIVE LOGIC)





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

SN74ALVC14 HEX SCHMITT-TRIGGER INVERTER





ABSOLUTE MAXIMUM RATINGS(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V _{CC}	Supply voltage range		-0.5	4.6	V
VI	Input voltage range ⁽²⁾		-0.5	4.6	V
Vo	Output voltage range ⁽²⁾⁽³⁾				
I _{IK}	Input clamp current	V _I < 0		-50	mA
I _{OK}	Output clamp current	V _O < 0		-50	mA
Io	Continuous output current		±50	mA	
	Continuous current through V _{CC} or GND			±100	mA
		D package		86	
0	Dooles so the supplies and a so (4)	DGV package		127	°C/W
θ_{JA}	Package thermal impedance (4)	NS package		76	
		PW package		113	
T _{stg}	Storage temperature range		-65	150	°C

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

RECOMMENDED OPERATING CONDITIONS⁽¹⁾

			MIN	MAX	UNIT		
V _{CC}	Supply voltage		2.3	3.6	V		
VI	Input voltage		0	3.6	V		
Vo	Output voltage		0	V _{CC}	V		
		V _{CC} = 2.3 V		-12			
I _{OH}	High-level output current	$V_{CC} = 2.7 \text{ V}$		-12	mA		
		$V_{CC} = 3 V$		-24			
		V _{CC} = 2.3 V		12			
I _{OL}	Low-level output current	$V_{CC} = 2.7 \text{ V}$		12	mA		
		$V_{CC} = 3 V$		24			
T_A	Operating free-air temperature		-40	85	°C		

⁽¹⁾ All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

⁽²⁾ The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

⁽³⁾ This value is limited to 4.6 V maximum.

⁽⁴⁾ The package thermal impedance is calculated in accordance with JESD 51-7.



ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{cc}	MIN	TYP ⁽¹⁾ MAX	UNIT		
		2.3 V	0.7	1.7			
V _{T+} Positive-going		2.7 V	0.8	2	V		
threshold		3 V	0.8	2	V		
		3.6 V	0.8	2			
		2.3 V	0.35	1.3			
V _{T-}		2.7 V	0.4	1.4	V		
Negative-going threshold		3 V	0.6	1.5	V		
		3.6 V	0.8	1.8			
		2.3 V	0.3	1			
ΔV_T Hysteresis (V _{T+} - V _{T-})		2.7 V	0.3	1.1			
		3 V	0.3	1.2	V		
(17 1-)		3.6 V	0.3	1.2			
	I _{OH} = 100 μA	2.3 V to 3.6 V	V _{CC} - 0.2				
	I _{OH} = -6 mA	2.3 V	2				
		2.3 V	1.7		V		
V _{OH}	I _{OH} = -12 mA	2.7 V	2.2				
		3 V	2.4				
	I _{OH} = -24 mA	3 V	2				
	I _{OL} = 100 μA	2.3 V to 3.6 V		0.2			
	I _{OL} = 6 mA	2.3 V		0.4			
V_{OL}	10	2.3 V		0.7	V		
	I _{OL} = 12 mA	2.7 V		0.4			
	I _{OL} = 24 mA	3 V		0.55			
I _I	V _I = V _{CC} or GND	3.6 V		±5	μΑ		
I _{cc}	$V_I = V_{CC}$ or GND, $I_O = 0$	3.6 V		10	μΑ		
ΔI_{CC}	One input at V _{CC} - 0.6 V, Other inputs at V _{CC} or GND	3 V to 3.6 V		750	μΑ		
C _i	V _I = V _{CC} or GND	3.3 V		4	pF		

⁽¹⁾ All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1 and Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 2.7 V		V_{CC} = 3.3 V \pm 0.3 V		UNIT
	(INFOT)		MIN	MAX	MIN	MAX	MIN	MAX	
t _{pd}	A	Υ	1	3.7		3.9	1	3.4	ns

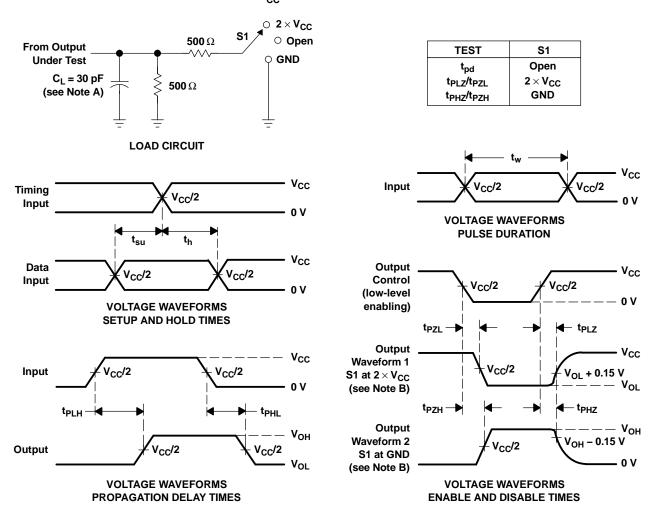
OPERATING CHARACTERISTICS

 $T_A = 25^{\circ}C$

PARAMETER		-	EST CONDITIONS	V _{CC} = 2.5 V	$V_{CC} = 3.3 \text{ V}$	UNIT
	PARAMETER		LOT CONDITIONS	TYP	TYP	ONIT
C_{pd}	Power dissipation capacitance per inverter	$C_L = 0$,	f = 10 MHz	27	31	pF



PARAMETER MEASUREMENT INFORMATION V_{CC} = 2.5 V \pm 0.2 V



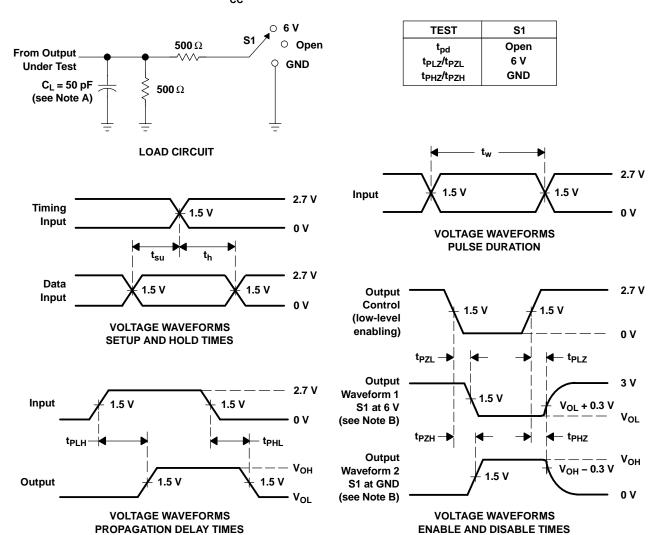
NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 $\Omega,\,t_f$ \leq 2 ns. t_f \leq 2 ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
- F. t_{PZL} and t_{PZH} are the same as t_{en}.
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION V_{CC} = 2.7 V AND 3.3 V \pm 0.3 V



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_{O} = 50 Ω , $t_{f} \leq$ 2.5 ns. $t_{f} \leq$ 2.5 ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
- F. t_{PZL} and t_{PZH} are the same as t_{en}.
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .
- H. All parameters and waveforms are not applicable to all devices.

Figure 2. Load Circuit and Voltage Waveforms

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74ALVC14D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVC14	Samples
SN74ALVC14DGVR	ACTIVE	TVSOP	DGV	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	VA14	Samples
SN74ALVC14DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVC14	Samples
SN74ALVC14DRG4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVC14	Samples
SN74ALVC14NSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVC14	Samples
SN74ALVC14PWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	VA14	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.



PACKAGE OPTION ADDENDUM

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALVC14DGVR	TVSOP	DGV	14	2000	330.0	12.4	6.8	4.0	1.6	8.0	12.0	Q1
SN74ALVC14DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74ALVC14NSR	so	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74ALVC14PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1



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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALVC14DGVR	TVSOP	DGV	14	2000	356.0	356.0	35.0
SN74ALVC14DR	SOIC	D	14	2500	356.0	356.0	35.0
SN74ALVC14NSR	so	NS	14	2000	356.0	356.0	35.0
SN74ALVC14PWR	TSSOP	PW	14	2000	356.0	356.0	35.0

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74ALVC14D	D	SOIC	14	50	506.6	8	3940	4.32

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
 - Sody length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



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